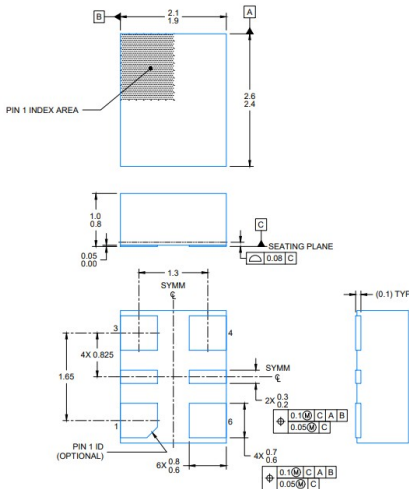
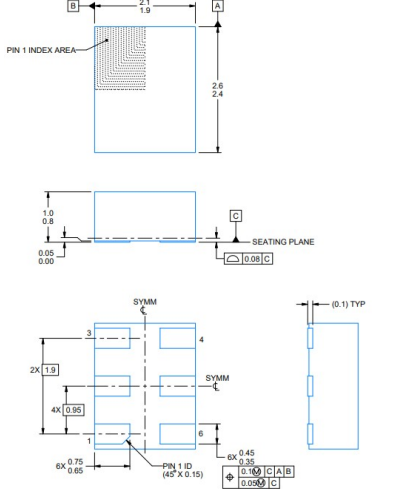
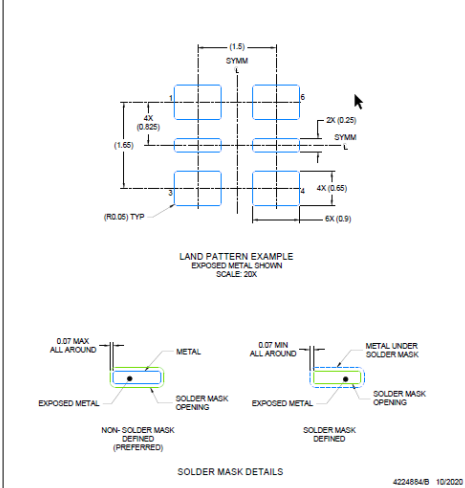
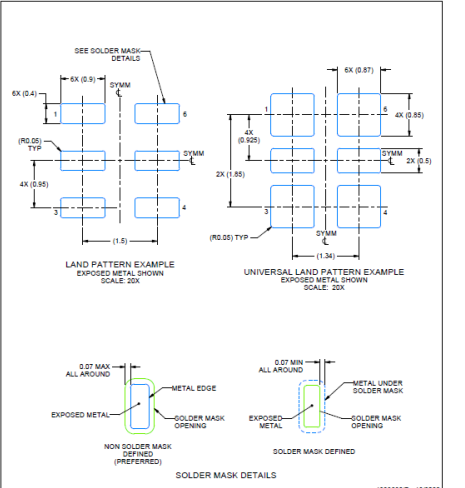
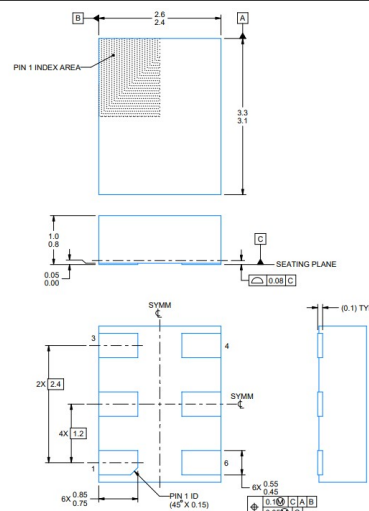
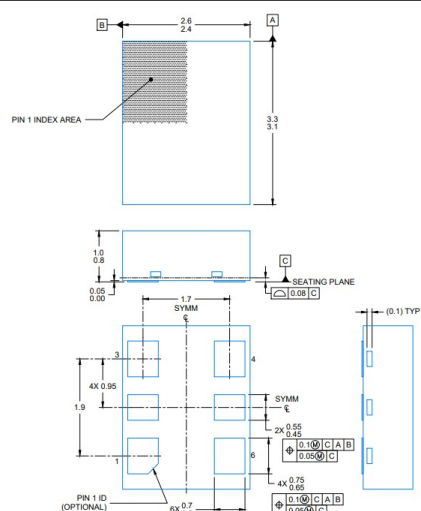


PCN Number: 20240318000.1		PCN Date: March 18, 2024			
Title: VSON Package Outline Drawing update for select devices					
Customer Contact:		Change Management team	Dept: Quality Services		
Proposed 1st Ship Date:		June 16, 2024	Sample requests accepted until: April 17, 2024		
*Sample requests received after April 17, 2024 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input checked="" type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the update on VSON Package Outline Drawing for the devices listed below. Devices will remain on current Assembly sites. The change will be reflected on the Data sheet after the PCN has expired.					
	Current		Proposed		
6DLF					
6DLF Land Pattern	<p>EXAMPLE BOARD LAYOUT VSON - 1 mm max height PLASTIC QUAD FLAT PACK-NO LEAD</p>  <p>SOLDER MASK DETAILS</p> <p>0.07 MAX ALL AROUND METAL EXPOSED METAL NON-SOLDER MASK DEFINED (PREFERRED) SOLDER MASK OPENING METAL UNDER SOLDER MASK EXPOSED METAL SOLDER MASK DEFINED</p> <p>4224554/B 10/2022</p>		<p>EXAMPLE BOARD LAYOUT VSON - 1 mm max height PLASTIC SMALL OUTLINE - NO LEAD</p>  <p>SOLDER MASK DETAILS</p> <p>0.07 MAX ALL AROUND METAL EXPOSED METAL NON-SOLDER MASK DEFINED (PREFERRED) SOLDER MASK OPENING METAL UNDER SOLDER MASK EXPOSED METAL SOLDER MASK DEFINED</p> <p>4224553/B 12/2023</p>		

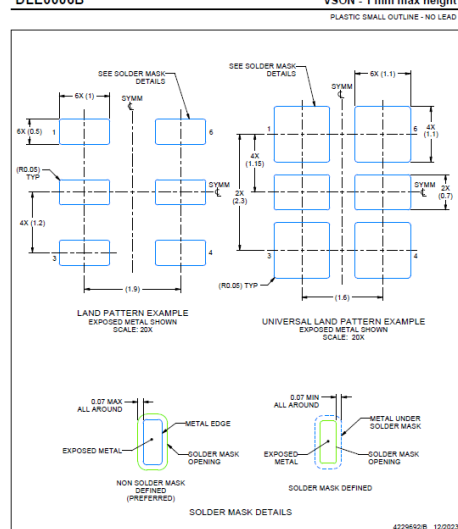
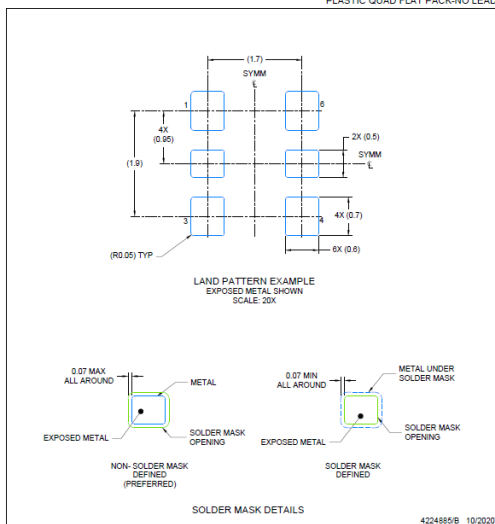


EXAMPLE BOARD LAYOUT
VSON - 1 mm max height
PLASTIC QUAD FLAT PACK-NO LEAD

EXAMPLE BOARD LAYOUT
VSON - 1 mm max height

DLE0006A

DLE0006B



EPOD Revision	DLF Exist LF PKG	DLF New LF PKG
DLF0006A	√	√
DLF0006B	√	√
	DLE Exist LF PKG	DLE New LF PKG
DLE0006A	√	X
DLE0006B	√	√

Reason for Change:

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

LMK6DA05184ADLER	LMK6DA15552ADLER	LMK6DA40000ADLFR	LMK6HA15625ADLER
LMK6DA05184ADLET	LMK6DA15552ADLET	LMK6DA40000ADLFT	LMK6HA15625ADLET
LMK6DA10000ADLFR	LMK6DA15625ADLFR	LMK6HA10000ADLER	LMK6HE40000ADLFR
LMK6DA10000ADLFT	LMK6DA15625ADLFT	LMK6HA10000ADLET	LMK6HE40000ADLFT
LMK6DA12288ADLER	LMK6DA20000ADLER	LMK6HA10000ADLFR	LMK6PA15625ADLER
LMK6DA12288ADLET	LMK6DA20000ADLET	LMK6HA10000ADLFT	LMK6PA15625ADLET
LMK6DA12500ADLFR	LMK6DA31250ADLFR	LMK6HA10000BDLFR	LMK6PA15625ADLFR
LMK6DA12500ADLFT	LMK6DA31250ADLFT	LMK6HA10000BDLFT	LMK6PA15625ADLFT

Qualification Report

Approve Date 27-FEBRUARY -2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name	Condition	Duration	Qual Device: <u>LMK6PA15625ADLET</u>
UFAST	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	Temperature Cycle	-55C/125C	700 Cycles	3/231/0
SD	PB-Free Solderability	PB-Free Solderability	-	1/22/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	(per mfg. Site specification)	Pass

QBS: Qual By Similarity

Qual Device LMK6PA15625ADLET is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.